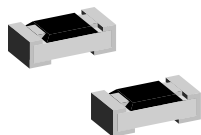


Thick Film Rectangular, Chip Resistor



FEATURES

- Metal glaze on high quality ceramic
- Protective overglaze
- SnPb contacts on Ni barrier layer flow solderable
- Automatic placement compatibility
- Applications: cellular phones, memory modules, PCMCIA cards

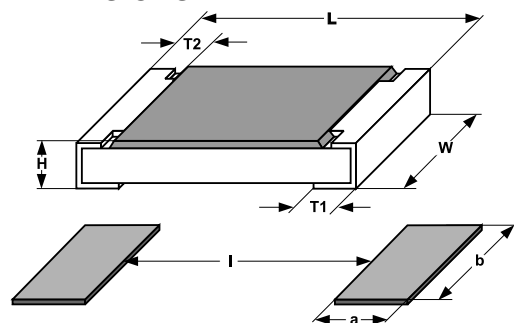
STANDARD ELECTRICAL SPECIFICATIONS							
MODEL	SIZE INCH	POWER RATING $P_{70^{\circ}\text{C}}$ W	LIMITING ELEMENT VOLTAGE MAX $V_{\cong}$	TEMPERATURE COEFFICIENT ppm/ $^{\circ}\text{C}$	TOLERANCE %	RESISTANCE RANGE Ω	E-SERIES
CRCW0201	0201	0.05	30	≤ 200	5	10R – 1M0	24

- Power rating depends on the max. temperature at the solder point, the component placement density and the substrate material
- Ask about extended value ranges.
- Marking: no marking

TECHNICAL SPECIFICATIONS		
PARAMETER	UNIT	CRCW0201
Rated Dissipation at 70 $^{\circ}\text{C}$	W	0.05
Limiting Element Voltage ¹⁾	$V_{\cong}$	30
Insulation Voltage (1min)	V_P	50
Insulation Resistance	Ω	$> 10^9$
Category Temperature Range	$^{\circ}\text{C}$	- 55 / + 125
Failure Rate	h^{-1}	$1 \cdot 10^{-9}$
Weight / 1000 pieces	g	0.17

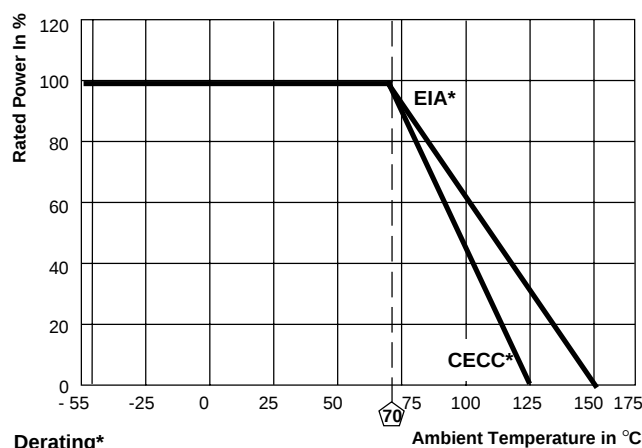
¹⁾Rated voltage: $\sqrt{P \times R}$

ORDERING INFORMATION				
CRCW0201	100R	J	200	P0
MODEL	RESISTANCE VALUE Ω	TOLERANCE $J = \pm 5\%$	TC ppm/ $^{\circ}\text{C}$	PACKAGING Papertape 10,000 pieces P0 = in Europe RT7 = in Americas/Asia

DIMENSIONS


SIZE	DIMENSIONS				
	L	W	H	T1	T2
mm	0.6 ±0.05	0.3 ±0.05	0.23 ±0.05	0.15 ±0.05	0.15 ±0.05
inch	0.024 ±.002	0.012 ±.002	0.009 ±.002	0.006 ±.002	0.006 ±.002

SIZE	SOLDER PAD DIMENSIONS		
	a	b	I
mm	0.28	0.43	0.23
inch	0.011	0.017	0.009



*There are differences in board layout and measurements between CECC and EIA.

PERFORMANCE

TEST	CONDITIONS OF TEST	TEST RESULTS
Endurance Test at 70°C IEC 60115-1 4.25.1	1000 hours at 70°C, 1.5 hours "ON", 0.5 hours "OFF"	≤ ± 3.0%
Endurance Test at UCT IEC 60115-1 4.25.3	1000 hours at 125°C without load	≤ ± 2.0%
Overload Test IEC 60115-1 4.13	Short time overload at 2.5 x rated voltage or 2 x limiting element voltage, 0.5 seconds	≤ ± 1.0%
Thermal Shock IEC 60115-1 4.19, IEC 60068-2-14	Rapid change between upper and lower category temperature	≤ ± 0.5%
Damp Heat Steady State IEC 60115-1 4.24, IEC 60068-2-3	56 days at 40°C and 93% relative humidity at $U \approx \sqrt{P/100 \times R}$	≤ ± 2.0%
Resistance to Soldering Heat IEC 60115-1 4.18, IEC 60068-2-20	10 seconds at 260°C solder bath temperature	≤ ± 1.0%

APPLICABLE SPECIFICATIONS

- CECC40000 / 40400 / EN 140 400 / IEC 60115 - 1
- EIA 575
- MIL-PRF-55342